

Docket No.: M4065.0248/P248-C
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Allen McTeer

Application No.: Not Yet Assigned

Group Art Unit: 2822

Filed: September 5, 2003

Examiner: Not yet Assigned

For: A MULTI-LAYERED COPPER BOND PAD
FOR AN INTEGRATED CIRCUIT (AS
AMENDED)

FIRST PRELIMINARY AMENDMENT

Box Non-Fee Amendment

Commissioner for Patents

Washington, DC 20231

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

In the Specification

Page 2, after the title, please insert --This application is a continuation of Application Ser. No. 10/079,858, filed February 22, 2002, which in turn is a divisional of Application Ser. No. 09/532,087, filed on March 21, 2000, the disclosure of both of which are incorporated by reference herein.--

In the Title

Please change the current title with – A MULTI-LAYERED COPPER BOND PAD FOR AN INTEGRATED CIRCUIT --.